



7th IEEE Electron Devices Technology and Manufacturing (EDTM) Conference 2023

Seoul, Korea, March 7th – 10th, 2023

<https://ewh.ieee.org/conf/edtm/2023/index.html>

The 7th Electron Devices Technology and Manufacturing Conference (IEEE EDTM 2023) will be held in Seoul, the capital and largest metropolis of Korea which is home to the headquarters of global-leading local companies. IEEE EDTM 2023 is a full four-day conference to be held during March 7–10, 2023. IEEE EDTM 2023 aims to be a premier global forum for researchers and engineers from around the world coming to share new discoveries and discuss about any device/manufacturing

Whether you are seeking to enhance brand recognition, reinforce your reputation as an industry leader, or establish a new business, IEEE EDTM 2023 sponsorship will enable you achieve your goals in this highly attended conference.

•Sponsorship Information

About Exhibition, We have a range of sponsorship packages designed to suit all your needs. Each allows you to showcase your products and services where the top marketing decision-makers and influencers network. The Exhibition booths are filled on first-come, first-served basis.

•How to reserve your sponsorship

1. Please download the Exhibition Application form and fill out and e-mail it to the IEEE EDTM 2023 Secretariat(edtm2023@edtm2023.org).
2. Pay the contribution within a month from invoice issue date.
3. Please send the receipt to the secretariat for confirmation of full payment.
4. All payments should be transferred to the bank account.

•Exhibition Information

Category	Exhibition Booth
Quantity	<input type="checkbox"/> KRW 2,000,000 X ()
VAT(10%)	A 10% VAT will be added for Korean companies that are required to issue a tax invoice.

* A 10% VAT will be added for Korean companies that are required to issue a tax invoice.

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Changrock Song, Ph.D.(SK Hynix)

TCP Chair:

Rino Choi, Ph.D.(Inha Univ. / KoNTRS)

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Secretariat:

Genicom Co., Ltd.

E-mail: edtm2023@edtm2023.org



[Sponsorship Benefit Summary]

BENEFITS	Diamond	Platinum	Gold	Silver	Bronze
Number of complementary exhibition booths *A first-come-first-served basis	2 (booth)	1 (booth)	1 (booth)	-	-
Company logo on the program book	0	0	0	0	0
Advertisement of the company in the program book	1 Page	1 Page	1 Page	1 Page	1/2 Page
Company logo on official website, E-newsletter screen at session rooms	0	0	0	0	0
Company logo featured on the banner at the venue	0	0	0	0	0
Number of complementary full conference registration	6	4	2	1	-
Number of complementary tutorial & short course registration	3	2	1	1	-

■ Type B (In-kind Support)

※ If the value of Type B is more than \$5,000, it will be provided a free registration benefit that is equivalent to the Type A preferential condition.

LEVEL	BENEFITS	VALUE
Banquet	<ul style="list-style-type: none"> - Promotion speech during the banquet - Logo on Program Book, Official Website, E-Newsletter, Screen at Session Room - Logo featured on the banner at the venue - Logo featured on the banner of the banquet 	Please contact a secretariat.
Souvenir	<ul style="list-style-type: none"> - Logo on Program Book, Official Website, E-Newsletter, Screen at Session Room - Logo featured on the banner at the venue - Logo featured on the banner of souvenir 	
Coffee Break	<ul style="list-style-type: none"> - Logo on Program Book, Official Website, E-Newsletter, Screen at Session Room - Logo featured on the banner at the venue - Put the company promotion leaflet during Coffee Break (on request) 	
Online Banner	<ul style="list-style-type: none"> - Logo on Official Website 	USD 85 KRW 1,000,000

■ Cancellation Policy

- Before December 30, 2022: Full payment will be refunded.
- Before January 15, 2023: 50% of full payment will be refunded.
- After January 15, 2023: Full payment will not be refunded.
- Cancellation of Exhibitors must be made in writing to the secretariat via e-mail.



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Exhibition Application Form

Please submit the below application form **no later than Jan. 20(Fri.), 2023**

IEEE EDTM 2023 Secretariat

E-mail: edtm2023@edtm2023.org / Tel: +82-42-472-7460 / Fax: +82-42-472-7459

1. Company Information

Company Name			
President		Person in Charge	
Department			
Address			
Zip Code		Country	
Tel		Fax	
E-mail			

2. Sponsorship (Please fill out the below)

Category	Quantity	VAT(10%)
Exhibition Booth	<input type="checkbox"/> KRW 2,000,000 X ()	A 10% VAT will be added for Korean companies that are required to issue a tax invoice.

3. Payment Method (Wire Transfer Only)

Account Holder	GENICOM CO., LTD 2023 IEEE EDTM
Account Number	661-910018-97105
Bank Name	KEB HANA BANK
Swift Code	KOEXKRSE
Bank Address	35, EULJI-RO, JUNG-GU, SEOUL, SOUTH KOREA
Branch	Jeonmin-Dong KEB HANA BANK

Name of Applicant :

Date :

Signature :



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Exhibition

•Exhibition Application

- Please submit the application form to the secretariat.
- Deadline: **January. 20(Fri.), 2023**

- ※ The details will be updated on the exhibition page.
- ※ A first-come-first-served basis

•Exhibition Application

Date	March 7 (Tue.) –10 (Fri.), 2023	
Location	COEX, Seoul, Korea	
Total Amount (per 1 Booth)	KRW 2,000,000 * A 10% VAT will be added for Korean companies that are required to issue a tax invoice.	
Size	2m (W) * 0.5m (L) * 2.5m (H)	
Benefits	Shell Scheme Package	
	Walls	Attach white wallpaper or painted plate to aluminum frame
	Company Name	0.3m (L) * 2.2m (H)
	Desk and Chairs	Desk : 1 / Chairs : 2
	Basic Electric Power Provided – Complementary 220V (2 pieces) 1KW Multi-taps – If additional power is needed, the fee has to be paid separately.	
	Logo on Official Website (1 page) Logo on the Program Book	
Image		

IEEE EDTM 2023 Secretariat

E-mail: edtm2023@edtm2023.org / Tel: +82-42-472-7460 / Fax: +82-42-472-7459